

SBOS212A – NOVEMBER, 2001

200MHz, CMOS OPERATIONAL AMPLIFIER

FEATURES

UNITY-GAIN BANDWIDTH: 450MHz
 WIDE BANDWIDTH: 200MHz GBW

● HIGH SLEW RATE: 360V/μs ● LOW NOISE: 5.8nV/√Hz

● EXCELLENT VIDEO PERFORMANCE: DIFF GAIN: 0.02%, DIFF PHASE: 0.05° 0.1dB GAIN FLATNESS: 75MHz

• INPUT RANGE INCLUDES GROUND

• RAIL-TO-RAIL OUTPUT (within 100mV)

● LOW INPUT BIAS CURRENT: 3pA

THERMAL SHUTDOWN

● SINGLE-SUPPLY OPERATING RANGE: 2.5V to 5.5V

MicroSIZE PACKAGES

APPLICATIONS

- VIDEO PROCESSING
- ULTRASOUND
- OPTICAL NETWORKING, TUNABLE LASERS
- PHOTODIODE TRANSIMPEDANCE AMPS
- ACTIVE FILTERS
- HIGH-SPEED INTEGRATORS
- ANALOG-TO-DIGITAL (A/D) CONVERTER INPUT BUFFERS
- DIGITAL-TO-ANALOG (D/A) CONVERTER OUTPUT AMPLIFIERS
- BARCODE SCANNERS
- COMMUNICATIONS

DESCRIPTION

The OPAx356 series high-speed, voltage-feedback CMOS operational amplifiers are designed for video and other applications requiring wide bandwidth. The OPAx356 is unity gain stable and can drive large output currents. Differential gain is 0.02% and differential phase is 0.05°. Quiescent current is only 8.3mA per channel.

OPAx356 is optimized for operation on single or dual supplies as low as 2.5V (±1.25V) and up to 5.5V (±2.75V). Common-mode input range for the OPAx356 extends 100mV below ground and up to 1.5V from V+. The output swing is within 100mV of the rails, supporting wide dynamic range.

The OPAx356 series is available in single (SOT23-5 and SO-8), and dual (MSOP-8 and SO-8) versions. Multichannel versions feature completely independent circuitry for lowest crosstalk and freedom from interaction. All are specified over the extended –40°C to +125°C range.

OPAx356 RELATED PRODUCTS

FEATURES	PRODUCT
200MHz, Rail-to-Rail Output, CMOS, Shutdown	OPAx355
38MHz, Rail-to-Rail Input/Output, CMOS	OPAx350
75MHz, Rail-to-Rail Output	OPAx631
150MHz, Rail-to-Rail Output	OPAx634
Differential Input/Output, 3.3V Supply	THS412x



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



ABSOLUTE MAXIMUM RATINGS(1)

Supply Voltage, V+ to V	7.5V
Signal Input Terminals, Voltage(2)	(V–) – 0.5V to (V+) + 0.5V
Current ⁽²⁾	10mA
Output Short-Circuit(3)	Continuous
Operating Temperature	–55°C to +150°C
Storage Temperature	65°C to +150°C
Junction Temperature	+160°C
Lead Temperature (soldering, 10s)	+300°C

NOTE: (1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied. (2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current limited to 10mA or less. (3) Short-circuit to ground one amplifier per package.



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

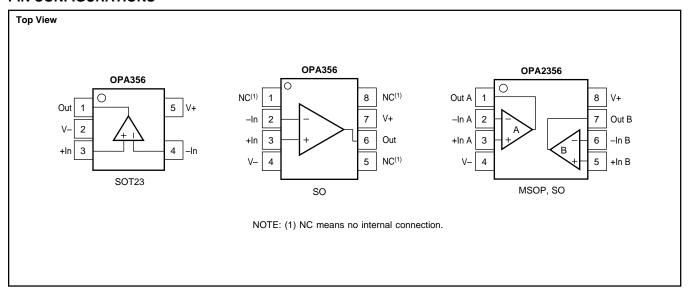
ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

PACKAGE/ORDERING INFORMATION

PRODUCT	PACKAGE-LEAD	PACKAGE DESIGNATOR ⁽¹⁾	SPECIFIED TEMPERATURE RANGE	PACKAGE MARKING	ORDERING NUMBER ⁽²⁾	TRANSPORT MEDIA, QUANTITY
OPA356AIDBV "	SOT23-5	DBV "	–40°C to +125°C	OAAI "	OPA356AIDBVT OPA356AIDBVR	Tape and Reel, 250 Tape and Reel, 3000
OPA356AID "	SO-8	D "	–40°C to +125°C "	OPA356A "	OPA356AID OPA356AIDR	Rails, 100 Tape and Reel, 2500
OPA2356AIDGK "	MSOP-8	DGK "	–40°C to +125°C "	AYI "	OPA2356AIDGKT OPA2356AIDGKR	Tape and Reel, 250 Tape and Reel, 2500
OPA2356AID	SO-8	D "	–40°C to +125°C "	OPA2356A "	OPA2356AID OPA2356AIDR	Rails, 100 Tape and Reel, 2500

NOTES: (1) For the most current specifications and package information, refer to our web site at www.ti.com. (2) Models labeled with "T" indicate smaller quantity tape and reel, "R" indicates large quantity tape and reel and "D" indicates rails of specified quantity.

PIN CONFIGURATIONS



ELECTRICAL CHARACTERISTICS: $V_S = +2.7V$ to +5.5V Single Supply

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+125^{\circ}C$.

At T_A = +25°C, R_F = 604 Ω , R_L = 150 Ω , Connected to $V_S/2$, unless otherwise noted.

				A356AIDBV, A A2356AIDGK,		
PARAMETER		CONDITION	MIN	TYP	MAX	UNITS
OFFSET VOLTAGE						
Input Offset Voltage	Vos	V _S = +5V		±2	±9	mV
		Specified Temperature Range			±15	mV
vs Temperature	dV _{os} /dT	Specified Temperature Range		± 7		μ ν/ ° C
vs Power Supply	PSRR	$V_S = +2.7V$ to +5.5V, $V_{CM} = V_S/2 - 0.15V$		±80	±350	μV/V
INPUT BIAS CURRENT						
Input Bias Current	I _B			3	±50	pА
Input Offset Current	Ios			±1	±50	pА
NOISE						
Input Noise Voltage Density	e _n	f = 1MHz		5.8		nV/√ Hz
Current Noise Density	in	f = 1MHz		50		fA/√Hz
INPUT VOLTAGE RANGE						
Common-Mode Voltage Range	V_{CM}		(V–) – 0.1		(V+) - 1.5	V
Common-Mode Rejection Ratio	CMRR	$V_S = +5.5V, -0.1V < V_{CM} < +4.0V$	66	80	(V+) - 1.5	dB
Common-wode Rejection Ratio	CIVILLI	Specified Temperature Range	66	80		dB dB
INDUT IMPEDANCE		opcomed remperature italiye	"			45
INPUT IMPEDANCE				4013 !! 4 5		٥ ا - ٦
Differential				10 ¹³ 1.5		Ω pF
Common-Mode				10 ¹³ 1.5		Ω pF
OPEN-LOOP GAIN		$V_S = +5V, 0.3V < V_O < 4.7V$	84	92		dB
	OPA356	$V_S = +5V$, $0.3V < V_O < 4.7V$	80			dB
	OPA2356	$V_S = +5V, 0.4V < V_O < 4.6V$	80			dB
FREQUENCY RESPONSE						
Small-Signal Bandwidth	f_{-3dB}	$G = +1, V_O = 100 \text{mVp-p}, R_F = 0\Omega$		450		MHz
	f_{-3dB}	$G = +2, V_O = 100 \text{mVp-p}, R_L = 50 \Omega$		100		MHz
	f_{-3dB}	$G = +2, V_O = 100 \text{mVp-p}, R_L = 150 \Omega$		170		MHz
	f_{-3dB}	$G = +2, V_O = 100 \text{mVp-p}, R_L = 1 \text{k}\Omega$		200		MHz
Gain-Bandwidth Product	GBW	$G = +10, R_L = 1k\Omega$		200		MHz
Bandwidth for 0.1dB Gain Flatness	f _{0.1dB}	$G = +2, V_O = 100 \text{mVp-p}, R_F = 560 \Omega$		75		MHz
Slew Rate	SR	$V_S = +5V$, G = +2, 4V Output Step		300/–360		V/μs
Rise-and-Fall Time		$G = +2$, $V_0 = 200 \text{mVp-p}$, 10% to 90%		2.4		ns
		$G = +2$, $V_0 = 2Vp-p$, 10% to 90%		8		ns
Settling Time, 0.1%		$V_S = +5V$, $G = +2$, 2V Output Step		30		ns
0.01%		$V_S = +5V$, $G = +2$, 2V Output Step		120		ns
Overload Recovery Time		V _{IN} • Gain = V _S		8		ns
Harmonic Distortion						
2 nd Harmonic		$G = +2$, $f = 1MHz$, $V_O = 2Vp-p$, $R_L = 200\Omega$		-81		dBc
3 rd Harmonic		$G = +2$, $f = 1MHz$, $V_O = 2Vp-p$, $R_L = 200\Omega$		-93		dBc
Differential Gain Error		NTSC, $R_L = 150\Omega$		0.02		. %
Differential Phase Error	0040050	NTSC, $R_L = 150\Omega$		0.05		degrees
Channel-to-Channel Crosstalk	OPA2356	f = 5MHz		-90		dB
OUTPUT						
Voltage Output Swing from Rail		$V_S = +5V, R_L = 150\Omega, A_{OL} > 84dB$		0.2	0.3	V
Voltage Output Swing from Rail		$V_S = +5V, R_L = 1k\Omega$		0.1		V
Voltage Output Swing from Rail	_	$I_O = \pm 100 \text{mA}$		0.8	1	V
Ouput Current, Continuous ⁽¹⁾	I _O		±60			mA
Maximum Output Current, Peak(1)	l _o	V _S = +5V	±100			mA
Maximum Output Current, Peak ⁽¹⁾	Io	V _S = +3V		±80		mA
Short Circuit Current				+250/-200		mA
Closed-Loop Output Impedance		f < 100kHz		0.02		Ω
POWER SUPPLY						
Specified Voltage Range	V_S		2.7		5.5	V
Operating Voltage Range				2.5 to 5.5		V
Quiescent Current (per amplifier)	ΙQ	$V_S = +5V, I_O = 0$		8.3	11	mA
		Specified Temperature Range			14	mA



ELECTRICAL CHARACTERISTICS: $V_S = +2.7V$ to +5.5V Single Supply (Cont.)

Boldface limits apply over the specified temperature range, $T_A = -40^{\circ}C$ to $+125^{\circ}C$.

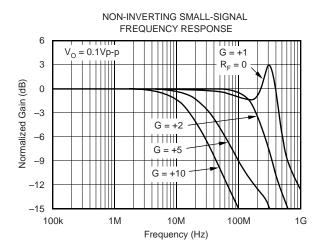
At T_A = +25°C, R_F = 604 Ω , R_L = 150 Ω , Connected to V_S/2, unless otherwise noted.

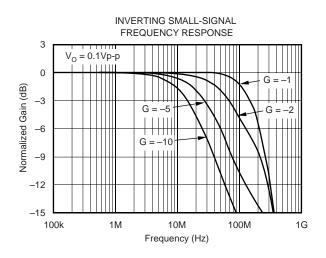
		OP OP			
PARAMETER	CONDITION	MIN	TYP	MAX	UNITS
THERMAL SHUTDOWN					
Junction Temperature					
Shutdown			160		°C
Reset from Shutdown			140		°C
TEMPERATURE RANGE					
Specified Range		-40		125	°C
Operating Range		-55		150	°C
Storage Range		-65		150	°C
Thermal Resistance θ					°C/W
SOT23-5, MSOP-8			150		°C/W
SO-8			125		°C/W

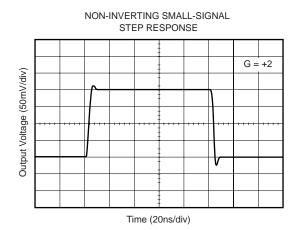
NOTES: (1) See typical characteristic "Output Voltage Swing vs Output Current".

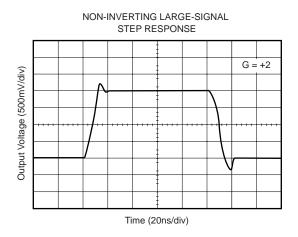


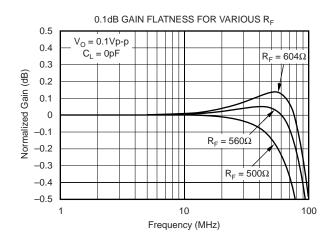
TYPICAL CHARACTERISTICS

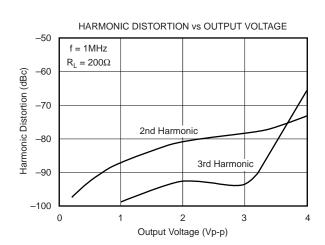


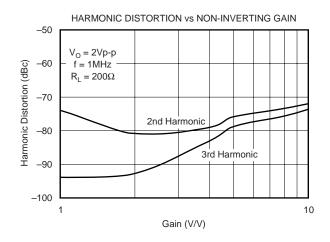


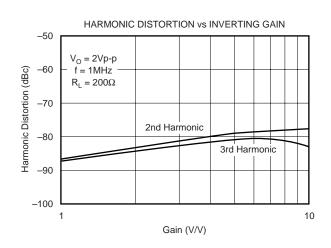


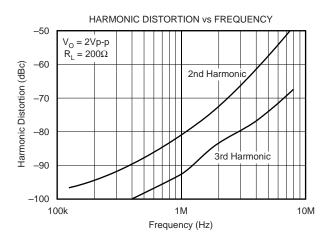


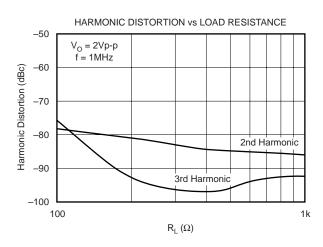


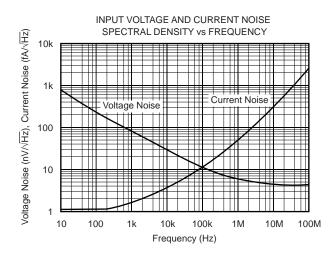


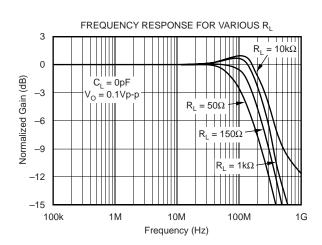




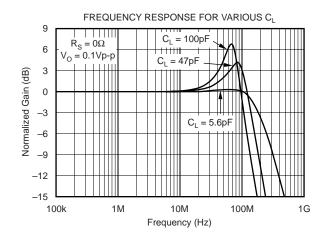


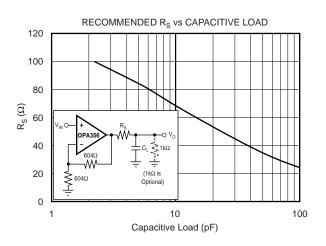


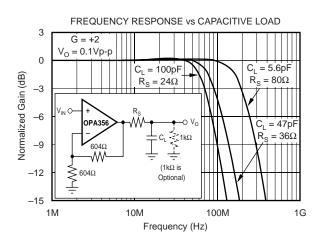


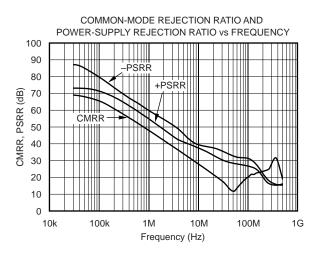


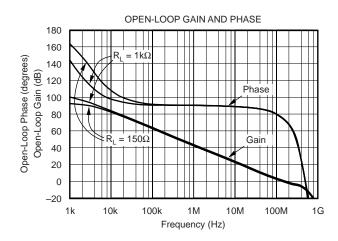


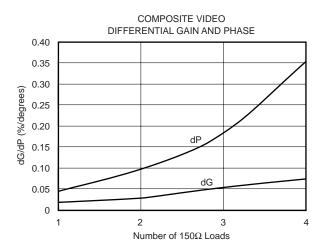


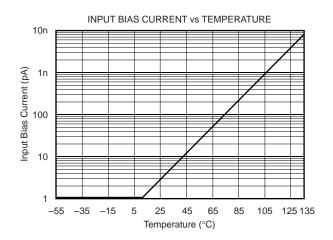


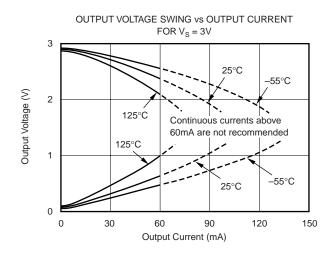


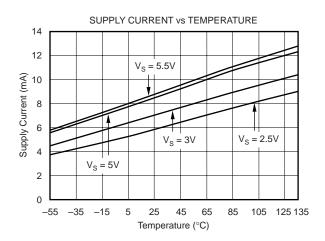


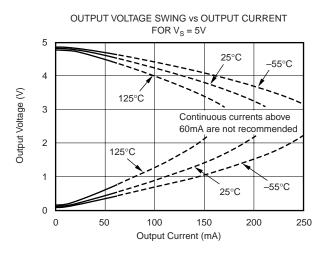


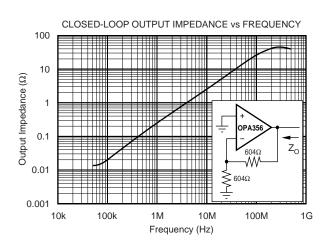


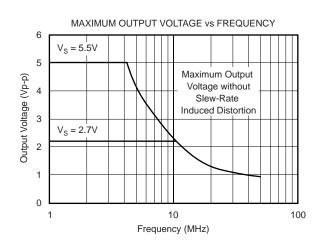




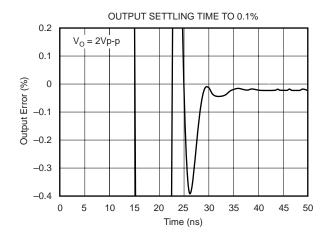


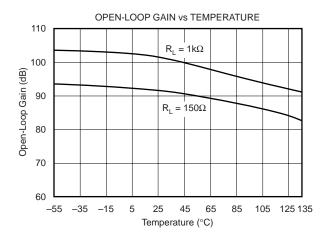


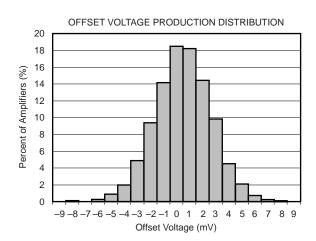


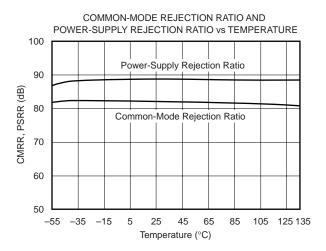


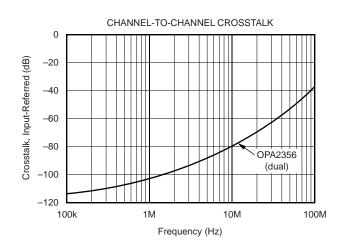














APPLICATIONS INFORMATION

The OPAx356 series is a CMOS, high-speed, voltage feed-back, operational amplifier designed for video and other general-purpose applications. It is available as a single or dual op amp.

The amplifier features a 200MHz gain bandwidth and $360V/\mu s$ slew rate, but it is unity-gain stable and can be operated as a +1V/V voltage follower.

Its input common-mode voltage range includes ground, allowing the OPAx356 to be used in virtually any single-supply application up to a supply voltage of +5.5V.

PCB LAYOUT

Good high-frequency PC board layout techniques should be employed for the OPAx356. Generous use of ground planes, short direct signal traces, and a suitable bypass capacitor located at the V+ pin will assure clean, stable operation. Large areas of copper also provide a means of dissipating heat that is generated within the amplifier in normal operation.

Sockets are definitely not recommended for use with any high-speed amplifier.

A $10\mu F$ ceramic bypass capacitor is the minimum recommended value; adding a $1\mu F$ or larger tantalum capacitor in parallel can be beneficial when driving a low-resistance load. Providing adequate bypass capacitance is essential to achieving very low harmonic and intermodulation distortion.

OPERATING VOLTAGE

The OPAx356 is specified over a power-supply range of $\pm 2.7V$ to $\pm 5.5V$ (± 1.35 to $\pm 2.75V$). However, the supply voltage may range from $\pm 2.5V$ to $\pm 5.5V$ ($\pm 1.25V$ to $\pm 2.75V$). Supply voltages higher than 7.5V (absolute maximum) can permanently damage the amplifier.

Parameters that vary significantly over supply voltage or temperature are shown in the "Typical Characteristics" section of this data sheet.

OUTPUT DRIVE

The OPAx356 output stage is capable of driving a standard back-terminated 75 Ω video cable. By back-terminating a transmission line, it does not exhibit a capacitive load to its driver. A properly back-terminated 75 Ω cable does not appear as capacitance; it presents only a 150 Ω resistive load to the OPAx356 output.

The output stage can supply high short-circuit current (typically over 200mA). Therefore, an on-chip thermal shutdown circuit is provided to protect the OPAx356 from dangerously high junction temperatures. At 160°C, the protection circuit will shut down the amplifier. Normal operation will resume when the junction temperature cools to below 140°C.

NOTE: It is not recommended to run a continuous DC current in excess of ± 60 mA. Refer to the graph of "Output Voltage Swing vs Output Current", shown in the "Typical Characteristics" section of this data sheet.

INPUT AND ESD PROTECTION

All OPAx356 pins are static protected with internal ESD protection diodes tied to the supplies, as shown in Figure 1.

These diodes will provide overdrive protection if the current is externally limited to 10mA by the source or by a resistor.

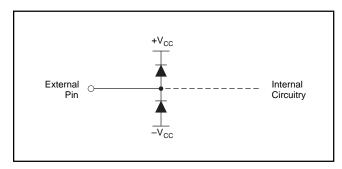
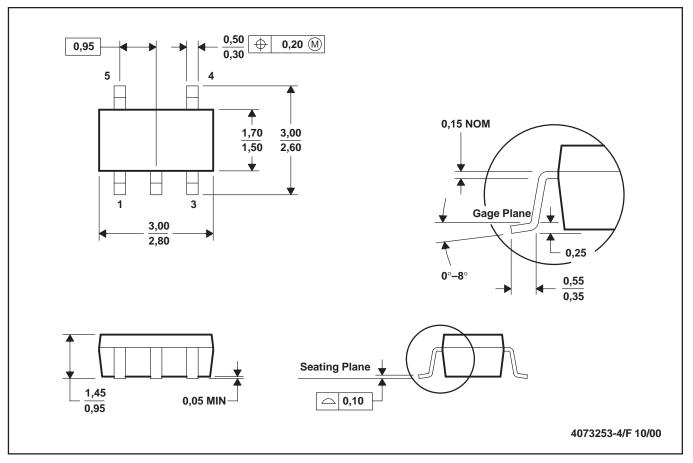


FIGURE 1. Internal ESD Protection.



DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE

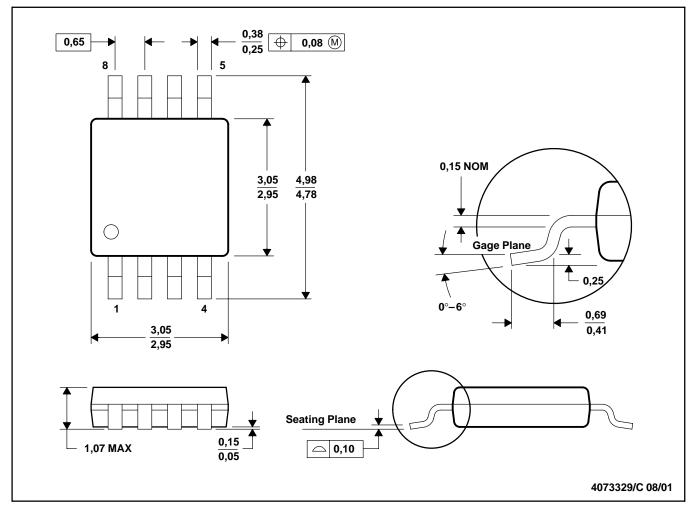


NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-178

DGK (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

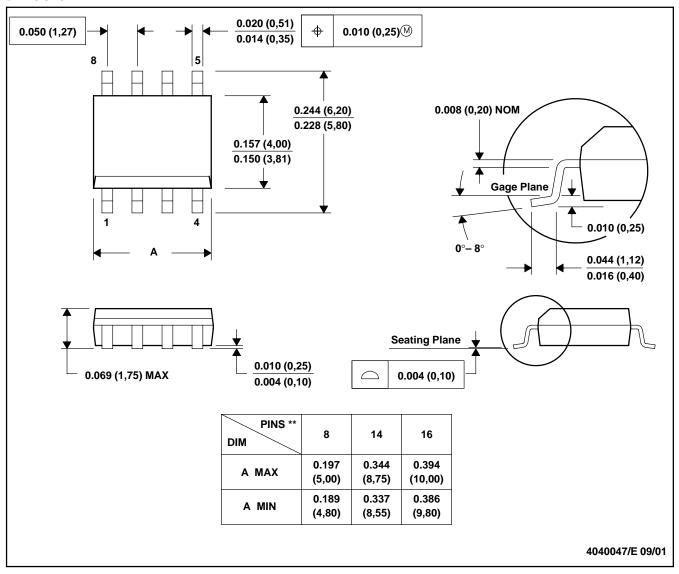
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-187



D (R-PDSO-G**)

8 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012





i.com 16-Feb-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
OPA2356AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2356AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2356AIDGKR	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2356AIDGKRG4	ACTIVE	MSOP	DGK	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2356AIDGKT	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2356AIDGKTG4	ACTIVE	MSOP	DGK	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2356AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA2356AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA356AID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA356AIDBVR	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA356AIDBVRG4	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA356AIDBVT	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA356AIDBVTG4	ACTIVE	SOT-23	DBV	5	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA356AIDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA356AIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
OPA356AIDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

16-Feb-2009

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

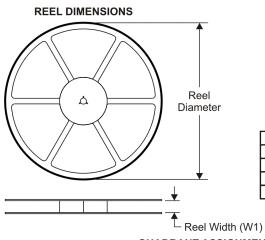
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20-Dec-2008

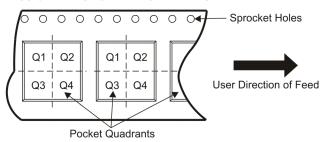
TAPE AND REEL INFORMATION



TAPE DIMENSIONS $\Phi \Phi \Phi \Phi \Phi$ \oplus Cavity → A0 **←**

	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

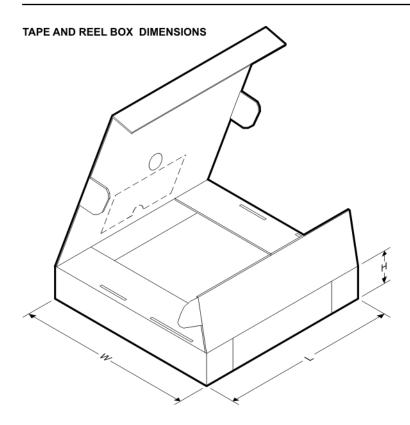
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2356AIDGKR	MSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2356AIDGKT	MSOP	DGK	8	250	180.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2356AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA356AIDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.2	3.1	1.39	4.0	8.0	Q3
OPA356AIDBVT	SOT-23	DBV	5	250	180.0	8.4	3.2	3.1	1.39	4.0	8.0	Q3
OPA356AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2356AIDGKR	MSOP	DGK	8	2500	346.0	346.0	29.0
OPA2356AIDGKT	MSOP	DGK	8	250	190.5	212.7	31.8
OPA2356AIDR	SOIC	D	8	2500	346.0	346.0	29.0
OPA356AIDBVR	SOT-23	DBV	5	3000	190.5	212.7	31.8
OPA356AIDBVT	SOT-23	DBV	5	250	190.5	212.7	31.8
OPA356AIDR	SOIC	D	8	2500	346.0	346.0	29.0

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